

Tin-Lead

SLOTOLET K 10-1

IMDS ID No. depending on alloy composition

Tin-Lead SLOTOLET K 10-1 is a strong acidic fluoride-free process for the deposition of matt tin-lead. The alloy composition can be varied over a wide range but the process has particular application for the eutectic mixture and low lead (5 - 15%) content. The chosen alloy composition is very stable over a wide current density range. Build up of organics in the deposit is low; the carbon content is ~ 0.005%. Solderability following ageing tests is very good.

The organic additives can be fully analysed allowing for control of possible organic contamination (e.g. PCB manufacture) and exact process monitoring and documentation.

The deposits from Tin-Lead SLOTOLET K 10-1 are very smooth, making it suitable for plating IC lead frames.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read these instructions carefully and follow recommendations given.

We reserve the right to make technical changes as necessary.

In the interests of safety, please pay attention to the R- and S- phrases on the drum label.

The shelf life of the additives is generally 18 months.

The date of production is taken from the first 3 figures of the batch number.

Figure 1 = year; figures 2-3 = month; figures 4-7 = batch number; (UK labels use a 4 digit year code).

For the storage of chemical products only the TRGS 514 and TRGS 515 Regulations must be followed. The Hazardous Goods Regulation (ADR/GGVS) are only valid for transportation and must not be applied to storage.

